

SEMICONDUCTOR

Green Product

200mW SOD-323 SURFACE MOUNT Small Outline Flat Lead Plastic Package High Voltage Switching Diode

Absolute Maximum Ratings T_A = 25°C unless otherwise noted

Symbol	Parameter	Value	Units	
\mathbf{P}_{D}	Power Dissipation	200	mW	
V _{RRM}	Maximum Repetitive Reverse Voltage	250	V	
T _{STG}	Storage Temperature Range	Temperature Range -65 to +150		
ΤJ	Operating Junction Temperature	+150	°C	
I _{F (AV)}	Average Rectified Forward Current	200	mA	
I _{FSM}	I _{FSM} Non-repetitive Peak Forward Current			
	Pulse Width = 1.0 Second	1.0	Α	
	Pulse Width = 1.0 µsecond	4.0	Α	

These ratings are limiting values above which the serviceability of the diode may be impaired.

Cathode Anode

SOD-323 Flat Lead

Specification Features:

- Flat Lead SOD-323 Small Outline Plastic Package
- Surface Device Type Mounting
- Moisture Sensitivity Level 1
- RoHS Compliant
- Green EMC
- Matte Tin(Sn) Lead Finish
- Band Indicates Cathode

DEVICE MARKING CODE:

Device Type	Device Marking		
BAV19WS	S5		
BAV20WS	S6		
BAV21WS	S7		



Electrical Characteristics $T_A = 25$ °C unless otherwise noted

Symbol	Parameter		Took Condition	Limits		Unit
			Test Condition	Min	Max	Unit
Ву	Breakdown Voltage	BAV19WS	I _R =100μA	120		Volts
		BAV20WS		200		Volts
		BAV21WS		250		Volts
I _R	Reverse Leakage Current	BAV19WS	V _R =100V		100	nA
		BAV20WS	V _R =150V		100	nA
		BAV21WS	V _R =200V		100	nA
V _F	Forward Voltage		I _F =100mA		1.0	Volts
			I _F =200mA		1.25	Volts
T _{RR}	Reverse Recovery Time		$I_F=I_R=30mA$			
			R _L =100Ω		50	nS
			I _{RR} =3mA			
С	Capacitance		V _R =0V, f=1M _{HZ}		5.0	pF

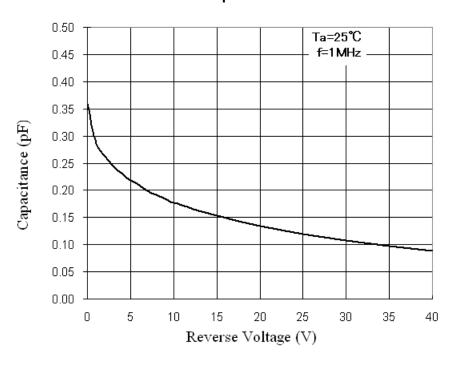
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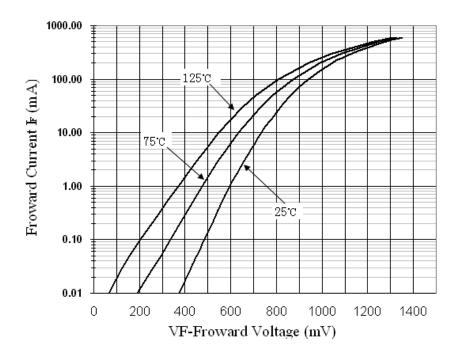


Typical Performance Characteristics

Total Capacitance



Forward Voltage vs Ambient Temperature

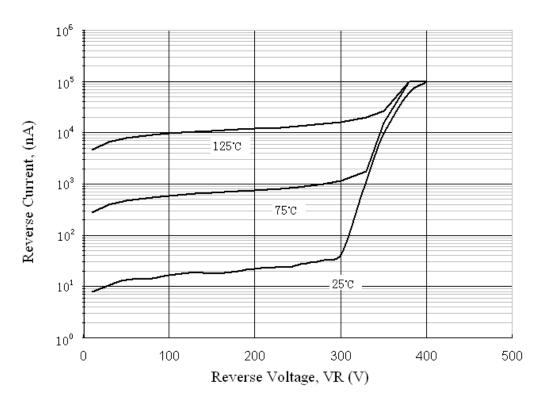


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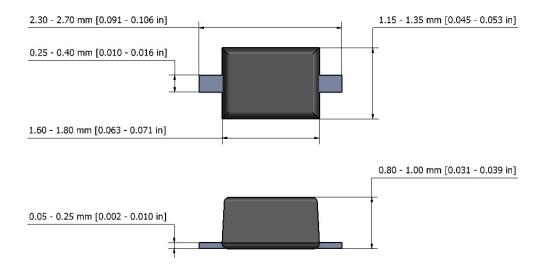
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Reverse Current vs Reverse VoltageReverse



SOD-323 Package Outline



NOTE:

- 1. The above package outline is similar to JEITA SC-90.
- 2. Dimensions are exclusive of Burrs, Mold Flash & Tie Bar extrusions.

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NOTICE

The information presented in this document is for reference only. Tak Cheong reserves the right to make changes without notice for the specification of the products displayed herein.

The product listed herein is designed to be used with ordinary electronic equipment or devices, and not designed to be used with equipment or devices which require high level of reliability and the malfunction of with would directly endanger human life (such as medical instruments, transportation equipment, aerospace machinery, nuclear-reactor controllers, fuel controllers and other safety devices), Tak Cheong Semiconductor Co., Ltd., or anyone on its behalf, assumes no responsibility or liability for any damagers resulting from such improper use of sale.

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